

Thailand Electronics Circuit Asia Show 2024



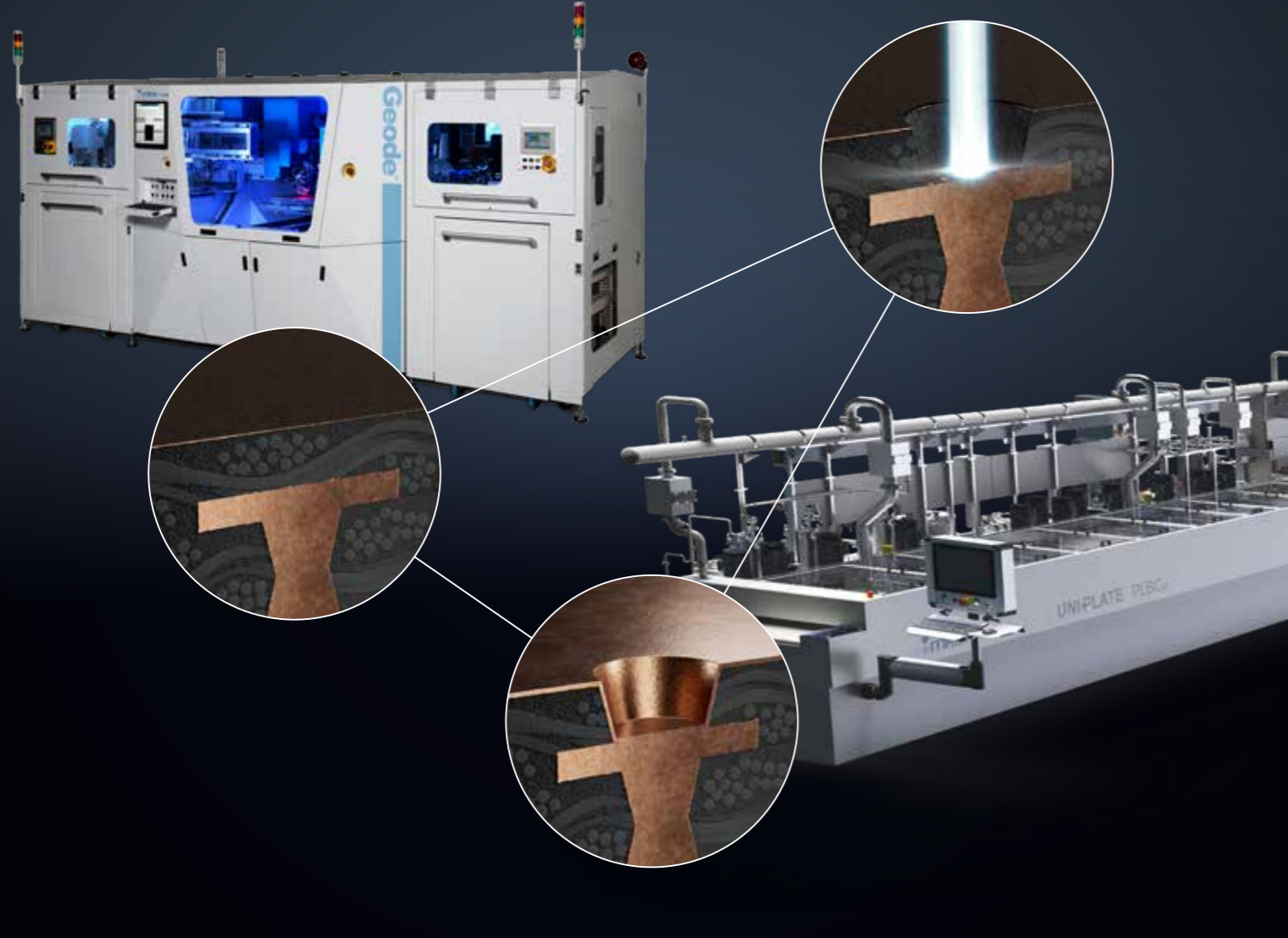
Highlights / Product Features

Electronics

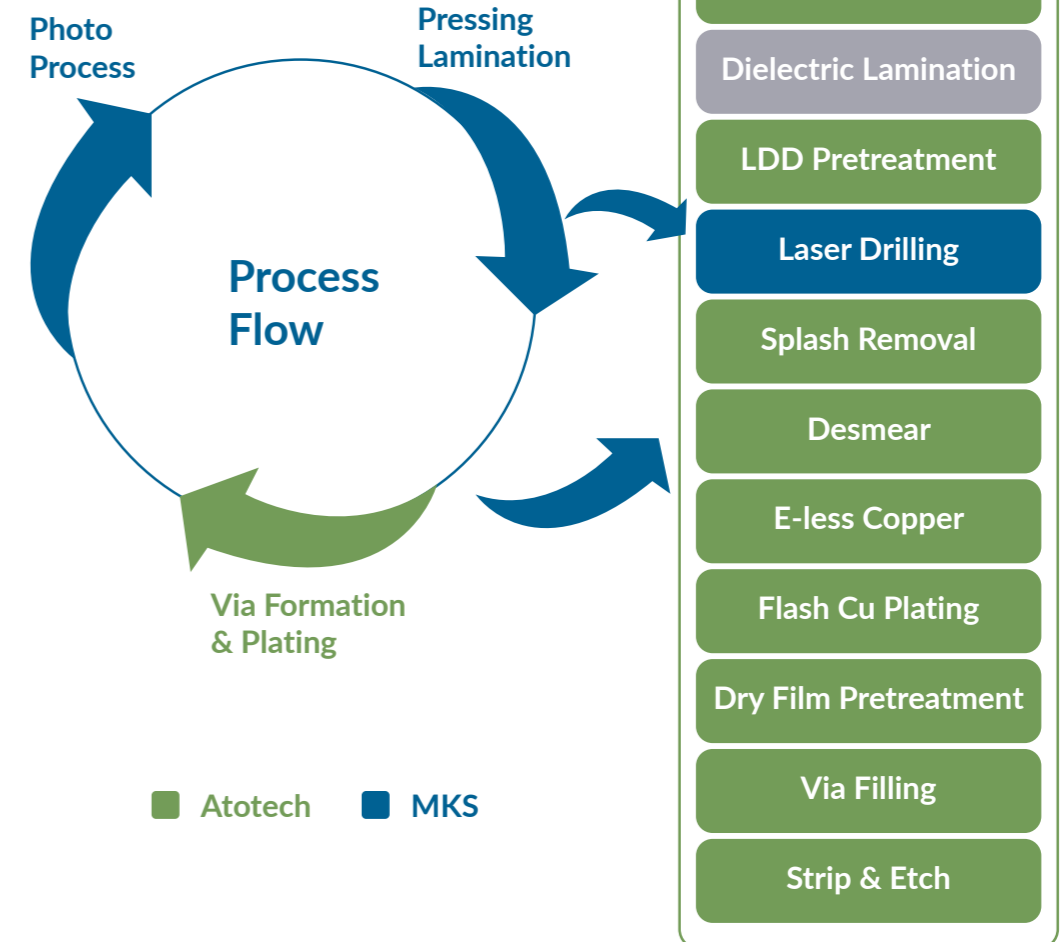
2024

atotech.com

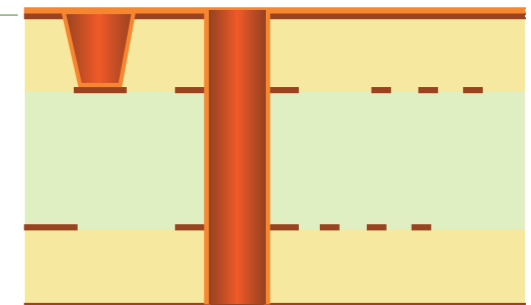
Optimize the Interconnect™



Optimize the InterconnectSM



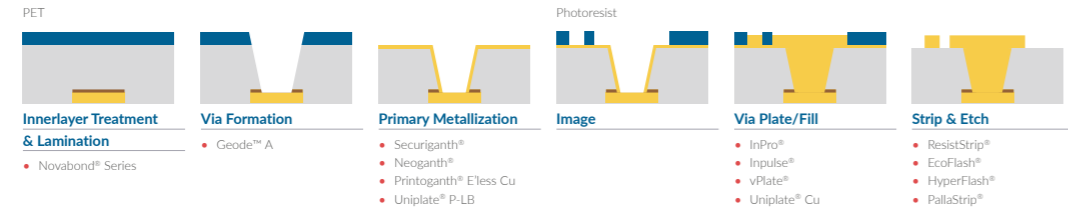
World-class drilling, copper metallization, plating and bonding for optimum performance and reliability results



New combined product offering

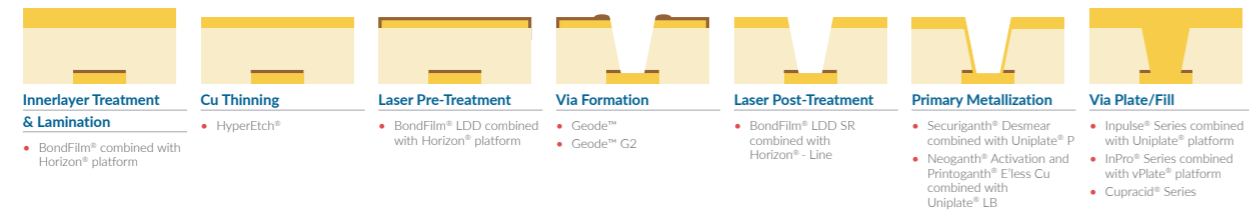
Package substrate

Production using CO₂ laser



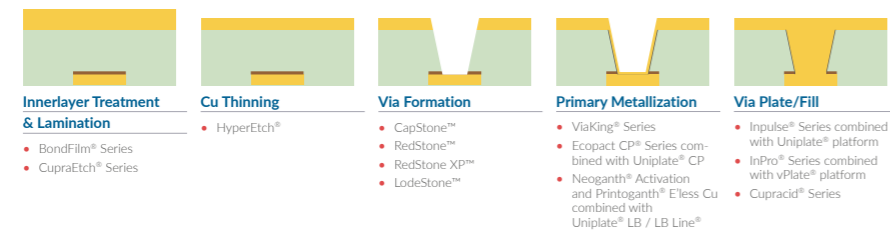
HDI

PCB production using CO₂ laser



FLEX

PCB production using UV laser



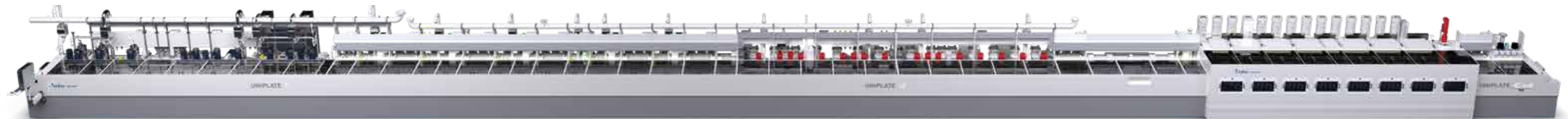
Introducing Geode™ A and CapStone™



Geode™ A
PCB Laser Drill System



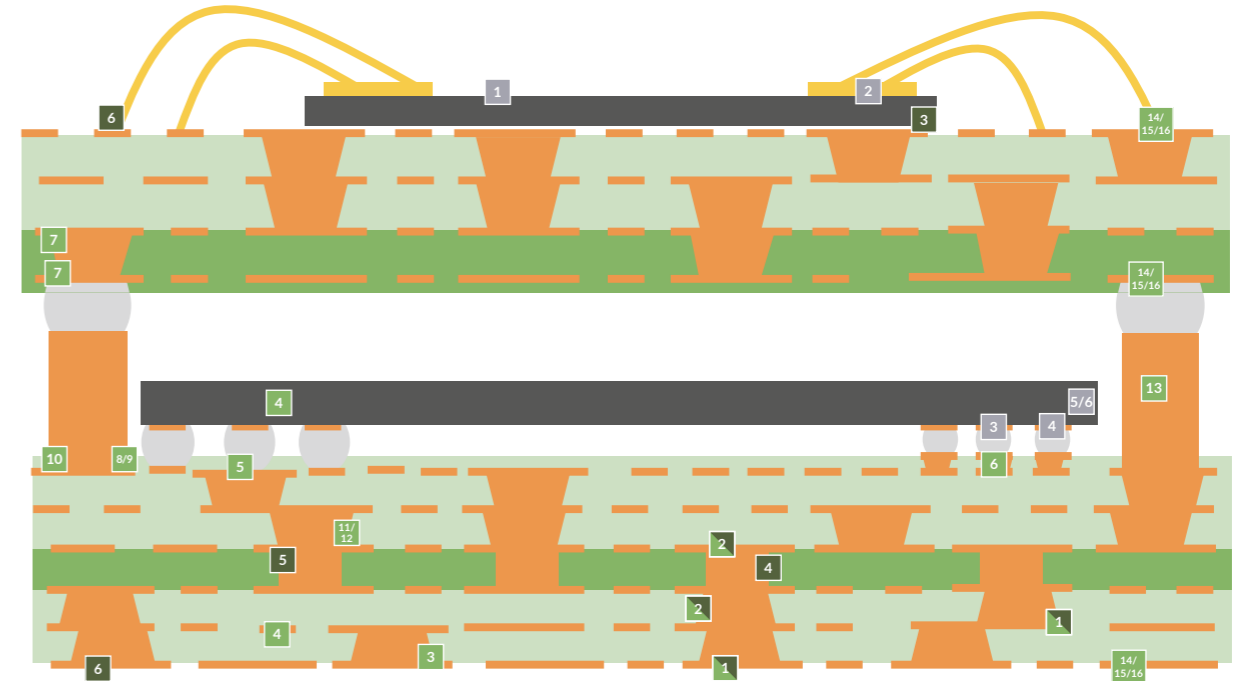
CapStone™
Flex PCB Laser Drill System



Electronics applications



Process chemicals for package substrates



Chips

Core and build-up layers

Outer layers

 Everplate® / Atomplate® / Atompure® Co Damascene Cu and Co plating	 Xenolyte® E'less deposition of NiPdAu and NiPd for wire bonding and soldering (UBM)	 Spherolyte® Cu Pillar High speed Cu pillar plating with Spherolyte® Cu/RDL	 Printoganth® MVTP1 / Printoganth® SAP Plus E'less Cu for SAP technology	 Securiganth® MV / Securiganth® SAP Wet chemical desmear for core and build-up materials	 VitroCoat GI / SigmaTech® GI / CupraTech® GI Plating on glass for next generation of interposers	 InPro® SAP3 VCP pattern BMV filling with excellent within-unit distribution at high current densities	 Via2® Embedded conductor substrate for line dimension <10µm	 SolderFill® Elytic solder deposition for solder paste replacement	 InPro® CPF Copper bump / pillar plating for FLU applications	 NovaBond® IT Non etching adhesion promoter	 ResistStrip® IC-Series Removes photoresist used for package substrate		
 Spherolyte® Cu TSV Cu ECD for through silicon vias with Spherolyte® TSV	 Spherolyte® RDL / Pillar-3 High purity copper depositions for pillar and RDL	 Innolyte® P / PLP High speed copper depositions for pillar and RDL at highest uniformity in PLP application	 InPro® THF Pattern through hole filling in VCP for core substrate production	 Impulse® 2THF High-speed Cu pulse panel plating for inclusion-free through via filling	 Nikotron® / Pallatron® / Aurotron® / Universal ASF II or ASF NiAu and NiPdAu for wire bonding and soldering	 EcoFlash® 5300 Differential etching for advanced SAP manufacturing	 EcoFlash® M100 Differential etch for mSAP	 PallaStrip® IC CN-free Pd remover	 CovalBond® Adhesion promoter to any organic dielectrics	 InPro® PI Cu pillar plating for high interconnect density	 PallaBond® Direct EP or EPAG on Cu for wire bonding and soldering	 Universal ASF II or ASF High reliable ENEPIG for wire bonding and soldering	 Stannatech® / Stannatech IC® Horizontal immersion tin plating for FC-BGA and FC-CSP

BGA = ball grid array · BMV = blind micro via · CSP = chip scale package · ECD = electrochemical deposition · ENEPIG = electroless nickel, electroless palladium, immersion gold · EP = electroless palladium · EPAG = electroless palladium, autocatalytic gold · FC = flip chip · mSAP = modified semi-additive process · SAP = semi-additive process · TSV = through silicon via · UBM = under bump metallization · VCP = vertical conveyorized plater